







APPLICABLE STANDARD					
Rating	Operating Temperature Range	-40 °C to 140 °C ⁽¹⁾		Storage Temperature Range	-10 °C to 60 °C ⁽²⁾
	Voltage	125 V AC ⁽³⁾		Storage Humidity Range	Relative humidity 60% max (Not dewed)
	Current	0.5 A		Operating Humidity Range	Relative humidity 85% max (Not dewed)
SPECIFICATIONS					
ITEM		TEST METHOD		REQUIREMENTS	QT AT
CONSTRUCTION					
General Examination		Examined visually and with a measuring instrument.		According to the drawing.	x x
Marking		Confirmed visually.			x x
ELECTRICAL CHARACTERISTICS					
Contact Resistance		Measured at 100 mA MAX.(DC or 1000Hz)		65mΩ MAX.	x —
Insulation Resistance		Measured at 250 V DC.		1000 MΩ MIN.	x —
Voltage Proof		375 V AC applied for 1 min.		No flashover or breakdown.	x —
MECHANICAL CHARACTERISTICS					
Mating and Unmating Forces		Measured with an applicable connector.		Mating Force: 40 N MAX. Unmating Force: 4.4 N MIN.	x —
Mechanical Operation		Mated and unmated 10 times.		①Contact Resistance : 75mΩ MAX. ②No damage, cracks or looseness of parts.	x —
Vibration		Frequency 50~100 → 100~150 → 150~300Hz Acceleration 98 → 98~294 → 294 m/s ² 1 cycle 3 min 3 h for 3 axial directions ⁽⁴⁾		①No electrical discontinuity of more than 1 μs. ②No damage, cracks or looseness of parts.	x —
Shock		Acceleration 980 m/s ² , duration of pulse 6 ms at 3 times for 3 axial directions.			x —
ENVIRONMENTAL CHARACTERISTICS					
Damp Heat (Steady state)		Exposed at 60±2 °C, 90 ~ 95 %, 1000 h.		①Contact Resistance : 75mΩ MAX. ②Insulation Resistance : 1000 MΩ MIN. 	x —
Rapid Change of Temperature		Temperature -40 → +140 °C Time 30 → 30 min. under 1000 cycles. (Relocation time to chamber : within 2~3 MIN)		③No damage, cracks or looseness of parts.	x —
Cold		Exposed at -40°C, 1000 h		①Contact Resistance : 75mΩ MAX.	x —
Dry Heat		Exposed at 140°C, 1000 h		②No damage, cracks or looseness of parts.	x —
Sulfur Dioxide		Exposed at 40±2°C, 80±5%RH, 25±5ppm  for 96 h.		Contact Resistance : 75mΩ MAX.	x —
Resistance to Soldering Heat		1)Reflow soldering : Peak TMP : 260°C MAX Reflow TMP: 220°C MIN for 60sec 		No deformation of case of excessive looseness of the terminal.	x —
Solderability		Soldered at solder temperature 240±3°C for immersion duration, 3 sec.		A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed.	x —
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
	1	DIS-F-00016361	TK. ABE	HH. SHINDO	20221215
Notes ⁽¹⁾ Include temperature rise caused by current-carrying. ⁽²⁾ "STORAGE" means a long-term storage state for the unused product before assembly to PCB. ⁽³⁾ The creepage distance conforms to IEC 60664-1. Voltage effective value: 32V AC, Pollution Degree: 2 ⁽⁴⁾ Amplitude between connector mounting part and PCB is 0.05mm MAX.			APPROVED	HH. SHINDO	20190902
			CHECKED	KN. SHIBUYA	20190902
			DESIGNED	TK. ABE	20190902
			DRAWN	KI. YAMAZAKI	20190902
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.		ELC-376629-00-00
	SPECIFICATION SHEET		PART NO.	FX26-40P-1SV	
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL0576-1004-0-00	 1/1